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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
09/775,646	02/05/2001	Susumu Takahashi	202447US2	8312
22850	7590 10/05/2004	_	EXAMINER	
OBLON, SPIVAK, MCCLELLAND, MAIER & NEUSTADT, P.C.			SINGH, RACHNA	
	JKE STREET NDRIA, VA 22314		ART UNIT	PAPER NUMBER
	,		2176	

DATE MAILED: 10/05/2004

Please find below and/or attached an Office communication concerning this application or proceeding.



			1
	Application No.	Applicant(s)	CV.
Office Action 0	09/775,646	TAKAHASHI ET AL.	
Office Action Summary	Examiner	Art Unit	
	Rachna Singh	2176	
The MAILING DATE of this communication ap Period for Reply	ppears on the cover sheet w	ith the correspondence address	S
A SHORTENED STATUTORY PERIOD FOR REP THE MAILING DATE OF THIS COMMUNICATION - Extensions of time may be available under the provisions of 37 CFR 1 after SIX (6) MONTHS from the mailing date of this communication. - If the period for reply specified above is less than thirty (30) days, a re If NO period for reply is specified above, the maximum statutory perio - Failure to reply within the set or extended period for reply will, by statu. Any reply received by the Office later than three months after the mail earned patent term adjustment. See 37 CFR 1.704(b).	I. 1.136(a). In no event, however, may a lead of thire statutory minimum of thire d will apply and will expire SIX (6) MONute, cause the application to become Alead of the status of t	reply be timely filed ty (30) days will be considered timely. ITHS from the mailing date of this commun BANDONED (35 U.S.C. § 133).	ication.
Status			
1) Responsive to communication(s) filed on <u>05</u>			
· <u>—</u>	nis action is non-final.		
3) Since this application is in condition for allow closed in accordance with the practice under	•	•	rits is
Disposition of Claims			
4)⊠ Claim(s) <u>1-32</u> is/are pending in the applicatio	on.		
4a) Of the above claim(s) is/are withdr			
5) Claim(s) is/are allowed.			
6)⊠ Claim(s) <u>1-32</u> is/are rejected.			
7) Claim(s) is/are objected to.			
8) Claim(s) are subject to restriction and	or election requirement.		
Application Papers			
9) The specification is objected to by the Examir	ner.		
10) ☐ The drawing(s) filed on is/are: a) ☐ ac	ccepted or b) objected to	by the Examiner.	
Applicant may not request that any objection to the	ne drawing(s) be held in abeyar	nce. See 37 CFR 1.85(a).	
Replacement drawing sheet(s) including the corre	ection is required if the drawing	(s) is objected to. See 37 CFR 1.	121(d).
11)☐ The oath or declaration is objected to by the I	Examiner. Note the attached	d Office Action or form PTO-18	52.
Priority under 35 U.S.C. § 119			
12)⊠ Acknowledgment is made of a claim for foreig a)⊠ All b)□ Some * c)□ None of:		§ 119(a)-(d) or (f).	
1. Certified copies of the priority docume			
2. Certified copies of the priority docume		• • • • • • • • • • • • • • • • • • • •	
3. Copies of the certified copies of the pri	•	received in this National Stag	e
application from the International Bure * See the attached detailed Office action for a list		received	
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Attachment(s)			
Attachment(s) 1) X Notice of References Cited (PTO-892)	4) 🗌 Interview 9	Summary (PTO-413)	
2) Notice of Draftsperson's Patent Drawing Review (PTO-948)	Paper No(s)/Mail Date	
 Information Disclosure Statement(s) (PTO-1449 or PTO/SB/0 Paper No(s)/Mail Date 	8) 5) Notice of I 6) Other:	nformal Patent Application (PTO-152)	•
S. Patent and Trademark Office	-, <u></u>		

Art Unit: 2176

DETAILED ACTION

- 1. This action is responsive to communications: Application filed 02/05/01.
- 2. Claims 1-32 are pending. Claims 1, 9, 16, 23, and 28 are independent claims.

Priority

3. Acknowledgment is made of applicant's claim for foreign priority under 35 U.S.C. 119(a)-(d).

Claim Rejections - 35 USC § 102

4. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

- (e) the invention was described in (1) an application for patent, published under section 122(b), by another filed in the United States before the invention by the applicant for patent or (2) a patent granted on an application for patent by another filed in the United States before the invention by the applicant for patent, except that an international application filed under the treaty defined in section 351(a) shall have the effects for purposes of this subsection of an application filed in the United States only if the international application designated the United States and was published under Article 21(2) of such treaty in the English language.
- 5. Claims 1-2, 9-10, 16-17, 23, and 28 are rejected under 35 U.S.C. 102(e) as being anticipated by <u>Tamaki et al.</u>, US 2001/0014836 A1, 8/16/01 (filed 2/12/01, continuation filed 6/19/98).

In reference to claims 1, 9, 16, 23, and 28, Tamaki teaches a production planning system in which a production plan comprises a data storage unit for storing parts list information providing a list of required parts, a parts stock storage section indicating parts stock information. See abstract and page 6, paragraphs [0117]-[0118]. Compare to "a structured parts list information storage configured to store structured parts list information on components including a plurality of kinds of parts; a parts

Art Unit: 2176

Information storage configured to store parts information on a plurality of parts". Tamaki further teaches an adjusting means in which superfluous or deficient parts are identified from the parts stock information and parts information. Superfluous parts are eliminated as are deficient parts and the production planning system is adjusted accordingly. See page 6, paragraph [0117]-[0122] and page 18. Compare to "a parts information list creating and editing device configured to retrieve parts information on respective parts, stored in said structured parts list information storage, and to create a parts information list; and a structured parts information list creating and editing device configured to create an updated structured parts list information based on said parts information list created by said parts information list creating and editing device."

In reference to claims 2, 10, and 17, Tamaki teaches that the parts information in storage may include information regarding a name of the part, a feature such as quantity consumed, a cost evaluation module, etc. See figures 24-27.

Claim Rejections - 35 USC § 103

- 6. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
 - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 7. Claims 3-8, 11-15, 18-22, 24-27, and 29-32 are rejected under 35 U.S.C. 103(a) as being unpatentable over <u>Tamaki et al.</u>, US 2001/0014836 A1, 8/16/01 (filed 2/12/01, continuation filed 6/19/98) in view of <u>Tegethoff</u>, US 5,539,652, 7/23/96.

Art Unit: 2176

In reference to claims 3-8, Tamaki does not teach a compatibility prediction information output device configured to survey on predetermined items (i.e. packaging density, arrangement, and operation verification) based on parts information list created by parts information list creating/editing device and to create and output decision information for compatibility prediction based on results from said survey. Tegethoff, however, teaches a method for manufacturing test simulation in electronic circuit design. Tegethoff teaches a test simulator that simulates a manufacturing text of boards and multichip modules from design concept to aid the designer in selecting trade-offs in design. The methods models fault probabilities for the circuit design based on the components. Tegethoff further discloses the Manufacturing Test Simulator (MTSIM) which is a concurrent engineering simulation tool for manufacturing test, that is, a tool to predict manufacturing test behavior while a product is still being designed. See column 6. MTSIM uses pareto analysis in which a user can evaluate simulation results to determine faults, test coverage, etc. Pareto analysis can be done at three levels of abstraction including individual components, groups of components with the same part number, and groups of components. All part numbers are assigned a category based on level of integration and functionality. See column 11. Furthermore, Tegethoff teaches that he technology of circuit board assembly is evolving to support density demands of many modern circuit designs. Multi-chip modules and twelve-mil pitch surface mount technology (SMT) are frequently used to improve circuit density. SMT chip packages with lead counts of over 1000 are not uncommon. New fabrication processes are used to enable higher circuit densities usually have higher defect rates

Art Unit: 2176

than older low density fabrication technologies. Tegethoff teaches identifying defects in packaging densities. See columns 1-4. It would have been obvious to a person of ordinary skill in the art at the time of the invention to incorporate Tegethoff's prediction concerning operation, simulation, etc in a system of Tamaki's structured parts list because early prediction of manufacturing behavior drives design changes which optimize the product's manufacturability and testability, thus improving product quality and reducing cost and utilizing a parts list would help facilitate this prediction. See column 6 of Tegethoff.

Claims 11-15 are rejected under the same rationale used in claims 3, 5, 6, 7 and 8 respectively above.

Claims 18-22 are rejected under the same rationale used in claims 3, 5, 6, 7 and 8 respectively above.

Claims 24-27 are rejected under the same rationale used in claims 3, 5, 6, and 7 respectively above.

Claims 29-32 are rejected under the same rationale used in claims 3, 5, 6, and 7 respectively above.

Conclusion

8. The prior art made of record and not relied upon is considered pertinent to applicant's disclosure.

Coburn et al.

US 2004/0128120 A1

Gehlot

US 6,353,806 B1

Sekitani

US 6,633,787 B1

Page 6

Application/Control Number: 09/775,646

Art Unit: 2176

Bade et al.

US 2002/0059054 A1

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Rachna Singh whose telephone number is
 703.305.1952. Starting in mid-October, the Examiner can be reached at 571-272-4099.
 The examiner can normally be reached on M-F (8:30-5).

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Joseph Feild can be reached on 703.305.9792. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

RS 9/23/04

SUPERVISORY PATENT EXAMINER